

**A STUDY ON THERMAL MANAGEMENT™ IN ELECTRONIC  
PACKAGING COMPONENTS**

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## **ABSTRACT**

Thermal Management is the most important protection of the Integrated Circuit (IC) and electronic component. This is because TM is important to ensure or to provide the desired mechanical and environmental protection to ensure reliability and performance of the product. Thermal Management is one of the keys that had been purposes to the electronic packaging to cool and maintain the integrated circuit and electronic component. It is commonly believed that a significant fraction of electronic "failures" are directly related to thermally induced problems. As devices get smaller and power goes higher, electronics designers need to continually challenge traditional methods of design to develop more reliable product designs and Thermal Management be apply to extend the useful lifetime of the electronic product. Therefore if we want our phones, computers, radio, hand pone and any component to work well for a long time we must seriously consider thermal management when designing any component electronic.

## **ABSTRAK**

Pengurusan terma merupakan salah satu perlindungan utama dalam melindungi litar bersepadu dan komponen elektronik. Ini adalah kerana Pengurusan terma adalah penting dalam menyediakan keadaan mekanikal dan persekitaran yang terlindung dan sesuai untuk memastikan kebolehharian dan penampilan sesuatu produk. Pengurusan terma juga merupakan salah satu kunci yang telah diaplikasikan di dalam bungkusan elektronik untuk proses menyejuk serta menstabilkan litar bersepadu dan komponen-komponen elektronik. Adalah dipercayai bahawa sedikit kegagalan dalam alat elektronik adalah berkait rapat dengan masalah pengurangan terma. Oleh kerana peralatan elektronik semakin hari semakin kecil dan kuasa yang digunakan semakin meningkat, jurutera elektronik haruslah meneruskan tradisi cabaran untuk mereka cipta peralatan yang lebih boleh diharap dan pengurusan terma diaplikasikan untuk memastikan produk elektronik dapat digunakan untuk masa yang lebih panjang. Oleh itu sekiranya kita ingin memastikan telefon, komputer, radio, telefon bimbit dan komponen dapat digunakan dalam keadaan yang lebih baik pada masa yang lebih lama kita haruslah mengambil berat akan masalah terma sebelum mereka sebarang peralatan elektronik.

## **LIST OF CONTENT**

|                               | <b>Pages</b> |
|-------------------------------|--------------|
| <b>APPROVAL LETTER</b>        |              |
| <b>APPROVAL SHEET</b>         |              |
| <b>PROJECT TITLE</b>          |              |
| <b>DEDICATION</b>             |              |
| <b>ACKNOWLEDGEMENT</b>        | <b>ii</b>    |
| <b>ABSTRACT</b>               | <b>iii</b>   |
| <b>ABSTRAK</b>                | <b>iv</b>    |
| <b>LIST OF CONTENT</b>        | <b>v</b>     |
| <b>LIST OF FIGURE</b>         | <b>xii</b>   |
| <b>LIST OF TABLE</b>          | <b>xiv</b>   |
| <b>LIST OF GRAPH</b>          | <b>xv</b>    |
| <b>REFERENCES</b>             | <b>xvi</b>   |
| <br>                          |              |
| <b>CHAPTER 1 INTRODUCTION</b> | <b>1 - 3</b> |
| <b>1.1 ABOUT THE PROJECT</b>  | <b>1</b>     |
| <b>2.2 OBJECTIVES</b>         | <b>2</b>     |
| <b>2.3 METHODOLOGY</b>        | <b>3</b>     |

|            |  |           |
|------------|--|-----------|
| a)         | Conduction   | 24        |
| b)         | Convection   | 25        |
| c)         | Radiation  | 26        |
| d)         | Change Of Phase  | 27        |
| <b>2.6</b> | <b>PACKAGING</b>   | <b>28</b> |
| 2.6.1      | INTRODUCTION   | 29        |
| 2.6.2      | PACKAGE RELIABILITY  | 29        |
| 2.6.3      | RELIABILITY CONSIDERATIONS   | 30        |
| 2.6.4      | RELIABILITY DEFINITIONS  | 31        |
| 2.6.5      | INTERCONNECTION TOPOLOGY   | 32        |
| 2.6.6      | THROUGH-HOLE COMPONENTS  | 36        |
| 2.6.7      | SURFACE MOUNT COMPONENTS   | 36        |
| a)         | Chip Scale Packages (CSP)  | 37        |
| b)         | Component Size Comparison  | 39        |
| 2.6.8      | THERMAL STRESS   | 39        |
| 2.6.9      | COMBINED WAVE SOLDER AND SOLDER REFLOW                               | 40        |
| 2.6.10     | PURPOSE OF SOLDER PASTE  | 40        |
| 2.6.11     | TYPES OF SOLDER PASTE FLUXES   | 41        |
| 2.6.12     | COMPONENT PLACEMENT PRESSURE TECHNIQUES<br>OF SOLDER INTERCONNECTION | 42        |
| a)         | Local Component Heating  | 42        |
| b)         | Global Board Heating   | 42        |

|                                       |               |
|---------------------------------------|---------------|
| <b>CHAPTER 3 ELECTRONIC COMPONENT</b> | <b>44- 67</b> |
| <b>3.0 INTRODUCTION</b>               | <b>44</b>     |
| <b>3.1 ACTIVE DEVICE</b>              | <b>45</b>     |
| 3.1.1 DIODES                          | 45            |
| 3.1.2 LIGHT EMITTING DIODES (LED)     | 45            |
| 3.1.3 TRANSISTORS                     | 46            |
| 3.1.4 IC INTEGRATED CIRCUITS          | 46            |
| 3.1.5 MICROPROCESSORS                 | 47            |
| <br>                                  |               |
| <b>3.2 PASSIVE DEVICE</b>             | <b>47</b>     |
| 3.2.1 RESISTORS                       | 47            |
| a) Fixed value resistors              | 49            |
| b) Metal film or metal oxide          | 50            |
| c) Wirewound                          | 50            |
| d) Color code                         | 51            |
| e) Power rating                       | 53            |
| 3.2.2 CAPACITORS                      | 62            |
| 3.2.3 INDUCTORS                       | 63            |

|                  |  |               |
|------------------|--|---------------|
| <b>3.3</b>       | <b>COMPONENT TEST</b>                                | <b>64</b>     |
| 3.3.1            | THERMAL SHOCK (TEMPERATURE CYCLING)                  | 64            |
| 3.3.2            | OVERLOAD   | 64            |
| 3.3.3            | VISUAL EXAMINATION                                   | 65            |
| 3.3.4            | POWER CONDITIONING (BURN-IN)                         | 65            |
| 3.3.5            | RADIOGRAPHIC INSPECTION (X-RAY)                      | 66            |
| 3.3.6            | ELECTRICAL MEASUREMENTS (DWV, DCR, IR)               | 66            |
| 3.3.7            | VISUAL EXAMINATION (5X AND 10X )                     | 66            |
| 3.3.8            | VIBRATION AND TEMPERATURE CYCLING                    | 67            |
| 3.3.9            | HUMIDITY CYCLING AND TEMPERATURE-HUMIDITY<br>CYCLING | 67            |
| 3.3.10           | TEMPERATURE-HUMIDITY-BIAS (THB)                      | 67            |
| <br>             |  |               |
| <b>CHAPTER 4</b> | <b>EXPERIMENT AND RESULT</b>                         | <b>68-117</b> |
| <b>4.1</b>       | <b>INTRODUCTION</b>                                  | <b>68</b>     |
| <b>4.2</b>       | <b>OVERLOAD TEST</b>                                 | <b>71</b>     |
| 4.2.1            | <b>RESISTOR</b>                                      | <b>72</b>     |
| a)               | TASK ONE   | 73            |
| b)               | TASK TWO   | 77            |
| c)               | TASK THREE   | 79            |
| d)               | TASK FOUR  | 81            |
| e)               | TASK FIVE  | 82            |



|              |  |            |
|--------------|--|------------|
| f)           | TASK SIX                                   | 84         |
| g)           | TASK SEVEN                                 | 86         |
| h)           | TASK EIGHT                                 | 87         |
| i)           | TASK NINE                                  | 88         |
| 4.2.1.1      | DISCUSSION                                 | 87         |
| 4.2.1.2      | SOLUTION                                   | 90         |
| <b>4.2.2</b> | <b>VISUAL EXAMINATION</b>                  | <b>93</b>  |
| <b>4.2.3</b> | <b>CAPACITOR</b>                           | <b>100</b> |
| a)           | TASK ONE                                   | 100        |
| b)           | TASK TWO                                   | 103        |
| 4.2.3.1      | DISCUSSION                                 | 105        |
| a)           | CHARGING                                   | 105        |
| b)           | DURING DISCHARGING                         | 106        |
| c)           | EMERGENCY PROCEDURE                        | 107        |
| a)           | TASK ONE                                   | 108        |
| b)           | TASK TWO                                   | 108        |
| <b>4.3</b>   | <b>THERMAL SHOCK</b>                       | <b>109</b> |
| <b>4.3.1</b> | <b>BURN-IN TEST</b>                        | <b>109</b> |
| <b>4.3.2</b> | <b>RESISTOR TEMPERATURE CHARACTERISTIC</b> | <b>109</b> |
| <b>4.3.3</b> | <b>EXPERIMENT PROCEDURE</b>                | <b>111</b> |
| a)           | TASK ONE                                   | 112        |
| b)           | TASK TWO                                   | 114        |
| 4.3.3.1      | DISCUSSION                                 | 116        |

|  |                |
|--|----------------|
| <b>CHAPTER 5 CONCLUSION AND RECOMMENDATION</b> | <b>118-123</b> |
| <b>5.1 Conclusions</b>                         | <b>118</b>     |
| <b>5.2 Recommendation</b>                      | <b>121</b>     |
| <b>5.3 future works</b>                        | <b>122</b>     |

## LIST OF FIGURE

|  | <b>Pages</b> |
|--|--------------|
| FIGURE 2.1: Representation of surface irregularity   | 9            |
| FIGURE 2.2: T642/643 form-in-place thermally conductive gap fillers                                    | 14           |
| FIGURE 2.3: Failure Mechanism  | 15           |
| FIGURE 2.4: Overstress Mechanism   | 16           |
| FIGURE 2.5: Wear out Mechanisms  | 17           |
| FIGURE 2.6: Interconnection assembly   | 34           |
| FIGURE 3.1: Resistor symbol  | 48           |
| FIGURE 3.2: Carbon Film construction   | 49           |
| FIGURE 3.3: Resistor color band.   | 52           |
| FIGURE 3.4: Different size of resistor with different characteristic                                   | 53           |
| FIGURE 3.5: Temperature dependence of resistance for an alloy (left)<br>and a carbon resistor (right). | 57           |
| FIGURE 3.6: Holes and electron movement  | 60           |
| FIGURE 3.7: Basic Capacitor  | 63           |
| FIGURE 4.1: MATLAB command windows   | 69           |
| FIGURE 4.2: MATLAB features.   | 70           |
| FIGURE 4.3: A simple Circuit For Overload Resistor   | 72           |
| FIGURE 4.4: Characteristic of different resistor   | 91           |

|  |     |
|--|-----|
| FIGURE 4.5: Resistor with 5X magnifier                         | 93  |
| FIGURE 4.6: Resistor with 10X magnifier                        | 93  |
| FIGURE 4.7: New resistor with 5X magnifier                     | 94  |
| FIGURE 4.8: Burn resistor                                      | 94  |
| FIGURE 4.9: Burn resistor with 5X Magnifier                    | 95  |
| FIGURE 4.10: Burn resistor with 10X magnifier                  | 95  |
| FIGURE 4.11: Burn resistor with 20X magnifier                  | 96  |
| FIGURE 4.12: Burn resistor with 5X magnifier and high voltage  | 97  |
| FIGURE 4.13: Burn Resistor with 10X magnifier and high voltage | 97  |
| FIGURE 4.14: Cracking on the resistor package                  | 98  |
| FIGURE 4.15: Result of the overload test                       | 98  |
| FIGURE 4.16: Charging a capacitor                              | 100 |
| FIGURE 4.17: Current flow during charging                      | 105 |
| FIGURE 4.18 : Different Temperature Coefficient                | 117 |

## LIST OF TABLE

|   | <b>Pages</b> |
|---|--------------|
| TABLE 2.1: Case-sink and junction ambient thermal resistance<br>for various interface materials | 11           |
| TABLE 3.1: Color code   | 51           |
| TABLE 3.2: Tolerance Band   | 53           |
| TABLE 4.1: Table for resistor with one voltage increases every<br>ten minute                    | 73           |
| TABLE 4.2: Table for resistor with one voltage applied every five minute                        | 77           |
| TABLE 4.3: Table for resistor by applying one voltage every one minute                          | 79           |
| TABLE 4.4: Table for resistor with 14.14 voltages   | 81           |
| TABLE 4.5: Table for resistor with 17.65 V of voltage   | 82           |
| TABLE 4.6: Table for resistor with 20 voltages  | 84           |
| TABLE 4.7: Table for resistor with 30 voltage   | 86           |
| TABLE 4.8: Table for resistor with 40 Voltage   | 87           |
| TABLE 4.9: Table for resistor with 50 voltages  | 88           |
| TABLE 4.10: Overload Capacitor with 16 V  | 108          |
| TABLE 4.11: Overload capacitor with 16V and 55V   | 108          |
| TABLE 4.12: Resistance of resistor in different temperature                                     | 112          |
| TABLE 4.13: Temperature characteristic for different value of resistors                         | 115          |

## LIST OF GRAPH

|   | <b>Pages</b> |
|---|--------------|
| GRAPH 4.1 : The resistor versus current from ohm's law        | 74           |
| GRAPH 4.2: Graph current versus voltage for task one          | 76           |
| GRAPH 4.3: Current versus voltage for task two                | 78           |
| GRAPH 4.4: Current versus time for 17.65 voltages applied     | 83           |
| GRAPH 4.5: Current versus time for 20 V of Voltages           | 85           |
| GRAPH 4.6: Charging a capacitor with 100 $\Omega$ resistor    | 101          |
| GRAPH 4.7: Graph for current versus time                      | 102          |
| GRAPH 4.8: Charging a capacitor with 10k $\Omega$ of resistor | 103          |
| GRAPH 4.9: Current during charging                            | 104          |
| GRAPH 4.10: Resistance versus temperature                     | 113          |
| GRAPH 4.11: Resistance Vs Temperature                         | 116          |

## **REFERENCES**

### **APPENDIX A**

Thermal Design Consideration

### **APPENDIX B**

Package Reliability

### **APPENDIX C**

Precision Hermetic Metal Film Resistor

### **APPENDIX D**

Mounting Of surface Mount Components

# **CHAPTER 1**

## **INTRODUCTION**

### **1.1 ABOUT THE PROJECT**

The project is about a study on thermal management(TM) in electronic packaging component. The basic idea of this project are through quantitative methodologies which can be divide into experimental methodologies and computational methodologies. The experimental methodologies is a done by collecting data on actual response of the passive component that are test at difference type of failure mechanism. Example of passive component are resistor and capacitor. After the data are collected the computational method are analyse by using a Matrix Laboratory (MATLAB) software which can analyze the data and tranform or simulate its into a graph.



## **1.2 OBJECTIVES**

The project required a study and investigation of the thermal management on electronic packaging component especially on the passive component. The project also involves experimental work and simulation by using MATLAB. The specific objective of this study is to bring both theoretical and practical aspects of electronics engineering and basic experimental work by:

- a) Investigate the TM of the second level electronic packaging component on carbon resistor and capacitor using a hybrid, computational and experimental approach.
- b) Study the different types of electronic component or TM-Characteristics by using a data collection.
- c) Understand the basic idea of Analysis and experimental work in the laboratory.
- d) Understanding the simulation step by using MATLAB and do some analysis.

### **1.3 METHODOLOGY**

The first method is by making a literature review of the project. This literature review involves information regarding the thermal management in electronic packaging component. Then the project continues with experimental test with the selected component, preparation of the component and a location needed for experimental. Finally an analysis by using MATLAB by developing a simple program and analyzed the output.

## **CHAPTER 2**

### **LITERATURE REVIEW**

#### **2.1 GENERAL INFORMATION**

Nowadays Thermal Management <sup>TM</sup> is one of the most important way to protect the Integrated Circuit (IC) and the electronic component. TM is one of the important approaches to ensure or to provide the desired mechanical and environmental protection for reliability and performance. Thermal Management is one of the keys that had been purposes to the electronic packaging to cool and maintain the integrated circuit. There are two objectives of Thermal Management, and there are:

- a) To prevent catastrophic thermal failure.
- b) To extend the useful lifetime of the electronic system

Catastrophic thermal failure is usually the result of thermal fracture of a mechanical element or separation of leads. It can also result in semiconductor material failure due to overheating.

As devices get smaller and power goes higher, electronics designers need to continually challenge traditional methods of design to develop more reliable product designs and Thermal Management be apply to extend the useful lifetime of the electronic product.

## **2.2 THERMAL DESIGN CONSIDERATIONS**

There is a need to consider Thermal Design and Thermal Management due to the increasing power dissipation of modern electronic systems and their components. The demand for higher integration, which is placing more functionality and performance into smaller volumes that compounds the problems need to be associate with providing adequate cooling. Without adequate cooling there is risk of increased production line fallout and field failures in electronic component. Many strategies for improved cooling, such as heat sinks, higher airflow, fans and ventilation are counter-acting to the requirements of other product design considerations. [Steyer, 1994]

As System operating frequencies increase, electronic components must dissipate more power to accommodate the needed reduction in access time. Thermal considerations become increasingly important in designs as power consumption approaches the limits of the package power dissipation.

### **2.3 THERMAL INTERFACE MATERIALS**

Today's semiconductors, whether discrete power or logic ICs, are smaller and run faster, therefore they generate more heat. Some microprocessors dissipate power levels that were once the exclusive domain of discrete power devices, namely 10 to 25 watts. These power levels require thermal management techniques involving large capacity heat sinks, good airflow and careful management of thermal interface resistances. A well-designed thermal management program will keep operating temperatures within acceptable limits in order to optimize device performance and reliability.[Steyer, 1994]

Every component in microelectronic are kept within their operating temperature limits by transferring junction generated waste heat to the ambient environment, usually the surrounding room air or in the casing itself. This is best accomplished by attaching a heat sink to the component package surface thus increasing the heat transfer between the hot case and the cooling air. Heat sinks may be selected to provide optimum thermal performance. Once the correct heat sink has been selected, it must be carefully joined to the component package to ensure efficient heat transfer through this newly formed thermal interface. The rate of conductive heat transfer,  $Q$ , across the interface is given by:

$$Q = \frac{kA(T_c - T_s)}{L}$$

Where  $k$  is the thermal conductivity of the interface,  $A$  is the heat transfer area,  $L$  is the interface thickness and  $T_c$  and  $T_s$  are the device case and heat sink temperatures respectively. The thermal resistance of a joint,  $R_{c-s}$ , is given by

$$R_{c-s} = \frac{(T_c - T_s)}{Q}$$

And on rearrangement,

$$R_{c-s} = \frac{L}{kA}$$

Thus, the thermal resistance of the joint is directly proportional to the joint thickness and inversely proportional to the thermal conductivity of the medium making up the joint and to the size of the heat transfer area. Thermal resistance is minimized by making the joint as thin as possible, increasing joint thermal conductivity by eliminating interstitial air and making certain that both surfaces are in intimate contact.

Attaching a heat sink to a component package requires that two solid surfaces be brought together into intimate contact. Unfortunately, no matter how well prepared, solid surfaces are never really flat or smooth enough to permit intimate contact. All surfaces have a certain roughness due to microscopic hills and valleys as shown in Figure 2.1 A. Superimposed on this surface roughness is a macroscopic non-planarity in the form of a concave, convex or twisted shape as shown in Figure 2.1 B. As two such surfaces are brought together, only the hills of the surfaces come into physical contact. The valleys are separated and form air-filled gaps.



A. Surface roughness; B. Poor surface flatness

FIGURE 2.1: Representation of surface irregularity[Miksa, 1995]

When two typical electronic component surfaces are brought together, less than one percent of the surfaces make physical contact. There are as much as 99% of the surfaces is separated by a layer of interstitial air. Some heat is conducted through the physical contact points, but much more has to transfer through the air gaps. Since air is a poor conductor of heat, it should be replaced by more conductive material to increase the joint conductivity and thus improve heat flow across the thermal interface.

Several types of thermally conductive materials can be used to eliminate air gaps from a thermal interface, including greases, reactive compounds, elastomers and pressure sensitive adhesive films. All are designed to conform to surface irregularities. Thus eliminating air voids and improving heat flow through the thermal interface.